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DETAILED ACTION

This Office Action is in response to Applicant's Request for Continued Examination (RCE) dated 05/12/04.

Allowable Subject Matter

- 1. Claims 1-16 and 29-30 are allowed.
- The following is an examiner's statement of reasons for allowance: Recorded 2. Prior Art fails to disclose a method of forming an oxide region over a semiconductor substrate comprising: introducing nitrogen into the non-oxide material to form a nitrogen-comprising surface region layer across at least some of the exposed silicon surface of the semiconductor substrate, the surface region extending greater than zero angstroms an no greater than 10 angstroms beneath the exposed silicon surface; and after forming the nitrogen comprising layer, growing an oxide region from the at least some of the semiconductor substrate, the oxide region having a thickness of at least about 70 angstroms, the nitrogen of the nitrogen-comprising layer being dispersed within the oxide region as characteristics in claim 1. Recorded Prior Art fails to disclose a method of forming a pair of oxide regions over a semiconductor substrate comprising: introducing nitrogen to form a nitrogen-comprising oxide layer across at least some of the first oxide region and a nitrogen-comprising non-oxide layer across at least some of the second portion of the semiconductor substrate, the nitrogen-comprising oxide layer extending greater than zero and less than or equal to about 10 angstroms beneath a

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in claim 29.

surface of the first oxide region and the nitrogen-comprising non-oxide layer extending greater than zero and less than or equal to about 10 angstroms beneath the exposed surface of the second portion of the semiconductor substrate; after introducing nitrogen, growing a second oxide region from the at least some of the second portion of the semiconductor substrate, the second oxide region having a thickness of at least about 70 angstroms as characteristics in claim 12. Recorded Prior Art also fails to disclose a method of forming a pair of oxide region over a semiconductor substrate comprising: forming a first oxide layer over a first portion of the semiconductor substrate, a second portion of the semiconductor substrate having an exposed non-oxide material surface; introducing nitrogen into at least some of the first oxide layer and into at least some of the exposed non-oxide material across at least some of the second portion of the semiconductor substrate; and after introducing nitrogen, exposing the substrate to oxidizing conditions to grow a second oxide layer from the at least some of the second portion of the semiconductor substrate, the second oxide layer having a thickness exceeding a thickness of the first oxide layer after the exposing, the nitrogen introduced into the second portion being dispersed within the second oxide layer as characteristics

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3. Any comments considered necessary by applicant must be submitted no later than the payment of the issue fee and, to avoid processing delays, should preferably accompany the issue fee. Such submissions should be clearly labeled "Comments on Statement of Reasons for Allowance."

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4. Any inquiry concerning this communication or earlier communications from the examiner should be directed to Thanhha Pham whose telephone number is (571) 272-1696. The examiner can normally be reached on Monday and Thursday 9:00AM - 9:30PM.

If attempts to reach the examiner by telephone are unsuccessful, the examiner's supervisor, Carl Whitehead can be reached on (571) 272-1702. The fax phone number for the organization where this application or proceeding is assigned is 703-872-9306.

Information regarding the status of an application may be obtained from the Patent Application Information Retrieval (PAIR) system. Status information for published applications may be obtained from either Private PAIR or Public PAIR. Status information for unpublished applications is available through Private PAIR only. For more information about the PAIR system, see http://pair-direct.uspto.gov. Should you have questions on access to the Private PAIR system, contact the Electronic Business Center (EBC) at 866-217-9197 (toll-free).

Thanhha Pham